

In the Specification

Please amend the title as follows:

~~Board-On-Chip Packages, and Methods of Forming Board-On-Chip Packages~~

At page 1, before the "Technical Field" section, please insert:

RELATED PATENT DATA

This patent resulted from a continuation application of U.S. Patent Application Serial No. 09/389,844, which was filed September 2, 1999.

Please amend the paragraph beginning at line 8 of page 1 as follows:

A prior art method of forming a board-on-chip package (which can be generally referred to as a die package) is described with reference to Figs. 1-5. Referring first to Fig. 1, such illustrates a fragment of an assembly 10 comprising an insulative material substrate 12. Substrate 12 can comprise, for example, a circuit board, such as the type known in the art as FR 4™ (which can be obtained from Sumitomo of Japan), or BCB™ (which can be obtained from Toppan of Japan).

In the Drawings

Submitted herewith is a replacement of drawing sheet 4, together with a red-lined version of the drawing sheet (marked "annotated marked-up drawings") showing the changes in the replacement drawing sheet relative to the originally-filed drawing sheet. The change to drawing sheet 4 addresses a formality of the drawing and is not a substantive change. Applicant requests that the replacement sheet be entered in place of the originally-filed drawing sheet 4.